

All Current Exemptions

1 - Mercury in single capped (compact) fluorescent lamps not exceeding (per burner):

1(a) - For general lighting purposes < 30 W: 5 mg. Expires on 31 December 2011; 3,5 mg may be used per burner after 31 December 2011 until 31 December 2012; 2,5 mg shall be used per burner after 31 December 2012

1(b) - For general lighting purposes \geq 30 W and < 50 W: 5 mg. Expires on 31 December 2011; 3,5 mg may be used per burner after 31 December 2011

1(c) - For general lighting purposes \geq 50 W and < 150 W: 5 mg

1(d) - For general lighting purposes \geq 150 W: 15 mg

1(e) - For general lighting purposes with circular or square structural shape and tube diameter \leq 17 mm. No limitation of use until 31 December 2011; 7 mg may be used per burner after 31 December 2011

1(f) - For special purposes: 5 mg

2(a) - Mercury in double-capped linear fluorescent lamps for general lighting purposes not exceeding (per lamp):

2(a)(1) - Tri-band phosphor with normal lifetime and a tube diameter < 9 mm (e.g. T2): 5 mg. Expires on 31 December 2011; 4 mg may be used per lamp after 31 December 2011

2(a)(2) - Tri-band phosphor with normal lifetime and a tube diameter \geq 9 mm and \leq 17 mm (e.g. T5): 5 mg. Expires on 31 December 2011; 3 mg may be used per lamp after 31 December 2011

2(a)(3) - Tri-band phosphor with normal lifetime and a tube diameter > 17 mm and \leq 28 mm (e.g. T8): 5 mg. Expires on 31 December 2011; 3,5 mg may be used per lamp after 31 December 2011

2(a)(4) - Tri-band phosphor with normal lifetime and a tube diameter > 28 mm (e.g. T12): 5 mg. Expires on 31 December 2012; 3,5 mg may be used per lamp after 31 December 2012

2(a)(5) - Tri-band phosphor with long lifetime (\geq 25 000 h): 8 mg. Expires on 31 December 2011;
5 mg may be used per lamp after 31 December 2011

2(b) - Mercury in other fluorescent lamps not exceeding (per lamp):

2(b)(1) - Linear halophosphate lamps with tube > 28 mm (e.g. T10 and T12): 10 mg. Expires on 13 April 2012

2(b)(2) - Non-linear halophosphate lamps (all diameters): 15 mg. Expires on 13 April 2016

2(b)(3) - Non-linear tri-band phosphor lamps with tube diameter > 17 mm (e.g. T9). No limitation of use until 31 December 2011; 15 mg may be used per lamp after 31 December 2011

2(b)(4) - Lamps for other general lighting and special purposes (e.g. induction lamps). No limitation of use until 31 December 2011; 15 mg may be used per lamp after 31 December 2011

3 - Mercury in cold cathode fluorescent lamps and external electrode fluorescent lamps (CCFL and EEFL) for special purposes not exceeding (per lamp):

3(a) - Short length (≤ 500 mm). No limitation of use until 31 December 2011; 3,5 mg may be used per lamp after 31 December 2011

3(b) - Medium length (> 500 mm and $\leq 1\ 500$ mm). No limitation of use until 31 December 2011; 5 mg may be used per lamp after 31 December 2011

3(c) - Long length ($> 1\ 500$ mm). No limitation of use until 31 December 2011; 13 mg may be used per lamp after 31 December 2011

4(a) - Mercury in other low pressure discharge lamps (per lamp). No limitation of use until 31 December 2011; 15 mg may be used per lamp after 31 December 2011

4(b) - Mercury in High Pressure Sodium (vapour) lamps for general lighting purposes not exceeding (per burner) in lamps with improved colour rendering index $R_a > 60$:

4(b)-I $P \leq 155$ W. No limitation of use until 31 December 2011; 30 mg may be used per burner after 31 December 2011

4(b)-II 155 W $< P \leq 405$ W. No limitation of use until 31 December 2011; 40 mg may be used per burner after 31 December 2011

4(b)-III - $P > 405$ W. No limitation of use until 31 December 2011; 40 mg may be used per burner after 31 December 2011

4(c) - Mercury in other High Pressure Sodium (vapour) lamps for general lighting purposes not exceeding (per burner):

4(c)-I $P \leq 155$ W. No limitation of use until 31 December 2011; 25 mg may be used per burner after 31 December 2011

4(c)-II 155 W $< P \leq 405$ W. No limitation of use until 31 December 2011; 30 mg may be used per burner after 31 December 2011'

4(c)-III - $P > 405$ W. No limitation of use until 31 December 2011; 40 mg may be used per burner after 31 December 2011

4(d) - Mercury in High Pressure Mercury (vapour) lamps (HPMV). Expires on 13 April 2015

4(e) - Mercury in metal halide lamps (MH)

4(f) - Mercury in other discharge lamps for special purposes not specifically mentioned in this Annex

5(a) - Lead in glass of cathode ray tubes

5(b) - Lead in glass of fluorescent tubes not exceeding 0,2 % by weight

6(a) - Lead as an alloying element in steel for machining purposes and in galvanized steel containing up to 0,35 % lead by weight

6(b) - Lead as an alloying element in aluminium containing up to 0,4 % lead by weight

6(c) - Copper alloy containing up to 4 % lead by weight

7(a) - Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

7(b) - Lead in solders for servers, storage and storage array systems, network infrastructure equipment for switching, signalling, transmission, and network management for telecommunications

7(c)-I - Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound

7(c)-II - Lead in dielectric ceramic in capacitors for a rated voltage of 125 V AC or 250 V DC or higher

7(c)-III - Lead in dielectric ceramic in capacitors for a rated voltage of less than 125 V AC or 250 V DC. Expires on 1 January 2013 and after that date may be used in spare parts for EEE placed on the market before 1 January 2013

7(c)-IV - Lead in PZT based dielectric ceramic materials for capacitors being part of integrated circuits or discrete semiconductors

8(a) - Cadmium and its compounds in one shot pellet type thermal cut-offs. Expires on 1 January 2012 and after that date may be used in spare parts for EEE placed on the market before 1 January 2012

8(b) - Cadmium and its compounds in electrical contacts

9 - Hexavalent chromium as an anticorrosion agent of the carbon steel cooling system in absorption refrigerators up to 0,75 % by weight in the cooling solution

9(b) - Lead in bearing shells and bushes for refrigerant-containing compressors for heating, ventilation, air conditioning and refrigeration (HVACR) applications

11(a) - Lead used in C-press compliant pin connector systems. May be used in spare parts for EEE placed on the market before 24 September 2010

11(b) - Lead used in other than C-press compliant pin connector systems. Expires on 1 January 2013 and after that date may be used in spare parts for EEE placed on the market before 1 January 2013

12 - Lead as a coating material for the thermal conduction module C-ring. May be used in spare parts for EEE placed on the market before 24 September 2010

13(a) - Lead in white glasses used for optical applications

13(b) - Cadmium and lead in filter glasses and glasses used for reflectance standards

14 - Lead in solders consisting of more than two elements for the connection between the pins and the package of microprocessors with a lead content of more than 80 % and less than 85 % by weight. Expires on 1 January 2011 and after that date may be used in spare parts for EEE placed on the market before 1 January 2011

15 - Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit flip chip packages

16 - Lead in linear incandescent lamps with silicate coated tubes. Expires on 1 September 2013

17 - Lead halide as radiant agent in high intensity discharge (HID) lamps used for professional reprography applications

18(b) - Lead as activator in the fluorescent powder (1 % lead by weight or less) of discharge lamps when used as sun tanning lamps containing phosphors such as BSP (BaSi₂O₅:Pb)

21 - Lead and cadmium in printing inks for the application of enamels on glasses, such as borosilicate and soda lime glasses

23 - Lead in finishes of fine pitch components other than connectors with a pitch of 0,65 mm and less. May be used in spare parts for EEE placed on the market before 24 September 2010

24 - Lead in solders for the soldering to machined through hole discoidal and planar array ceramic multilayer capacitors

25 - Lead oxide in surface conduction electron emitter displays (SED) used in structural elements, notably in the seal frit and frit ring

29 - Lead bound in crystal glass as defined in Annex I (Categories 1, 2, 3 and 4) of Council Directive 69/493/EEC (1)

30 - Cadmium alloys as electrical/mechanical solder joints to electrical conductors located directly on the voice coil in transducers used in high-powered loudspeakers with sound pressure levels of 100 dB (A) and more

31 - Lead in soldering materials in mercury free flat fluorescent lamps (which e.g. are used for liquid crystal displays, design or industrial lighting)

32 - Lead oxide in seal frit used for making window assemblies for Argon and Krypton laser tubes

33 - Lead in solders for the soldering of thin copper wires of 100 µm diameter and less in power transformers

34 - Lead in cermet-based trimmer potentiometer elements

37 - Lead in the plating layer of high voltage diodes on the basis of a zinc borate glass body

38 - Cadmium and cadmium oxide in thick film pastes used on aluminium bonded beryllium oxide

39 - Cadmium in colour converting II-VI LEDs (< 10 µg Cd per mm² of light-emitting area) for use in solid state illumination or display systems. Expires on 1 July 2014

40 - Cadmium in photoresistors for analogue optocouplers applied in professional audio equipment. Expires on 31 December 2013